

In the Claims:

Please add the following claims:

1 41. An apparatus for forming a fusing structure to implement redundancy
2 circuits within integrated circuits on a substrate comprising the steps of:

3 means for forming one or more fuse links of a conductive material
4 above an insulating layer on said substrate with a formation of
5 gates of transistors within said integrated circuits;

6 means for forming a hard mask layer above said fuse links with a
7 formation of a hard mask layer above said gates;

8 means for forming sources and drains of the transistors of the
9 integrated circuits; and

10 means for placing a hard mask removal resist material above the
11 surface of the substrate having openings at said fuse links and
12 said gates; and

13 means for removing said hard mask on said fuse link
14 simultaneously with removing said hard mask from said gates.

1 42. The apparatus of claim 41 further comprising:

2 means for forming interlayer dielectric above the surface of the
3 substrate; and

4 means for forming self-aligned contacts to the sources and drains
5 of the integrated circuits; and

6 means for forming an opening above the fuse links.

1 43. The apparatus of claim 41 wherein said conductive material is selected
2 from a group of conductive materials consisting of metals, heavily doped
3 polycrystalline silicon, and alloys of metals and heavily doped
4 polycrystalline silicon.

1 44. The apparatus of claim 41 wherein said insulating layer above which said
2 fuse links are formed is a field oxide.

1 45. The apparatus of claim 41 wherein said redundancy circuit is a column of
2 a DRAM array.

1 46. The apparatus of claim 41 wherein said redundancy circuit is a row of a
2 DRAM array.

1 47. The apparatus of claim 41 wherein the opening in the interlayer dielectric
2 is formed such that said interlayer dielectric between a bottom portion of
3 said opening and said fuse links are transparent to allow destruction of
4 said fuse links.

1 48. The apparatus of claim 41 wherein said hard mask on said fuse links are a
2 thickness that allows reliable destruction of said fuse links.